







(0,80 mm) .0315"

MICRO TIGER EYE" HEADER

TEM. TEM-DH Mates with: SEM, SEML

TEMS Mates with: SEMS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?TEM or www.samtec.com?TEMS

Insulator Material: Black Liquid Crystal Polymer Terminal Material:

Phosphor Bronze

Plating:
Au or Sn over 50μ" (1,27 μm) Ni
Operating Temp Range:
-55°C to +125°C

Current Rating: 2.6 A per pin (1 pin powered per row) **RoHS Compliant:**

Processing: Lead-Free Solderable:

SMT Lead Coplanarity: (0,10 mm) .004" max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



02 **PER ROW STRIP** TEM 05, 10, 15, 20, 25 = Tiger Eye™ Strip 30, 35, 40, 45, 50 (TEM only) TEMS (Standard sizes) = Tiger Eye^¹ Slim Strip (No. of Positions - x (0,80) .0315) 02 + (3,35) .132 000000000 (0,24) 000000000 TEMS (0,80) → (0,80) .0315 (No. of Positions x $(0.80) \cdot 0.0315) + (9.00) \cdot .354$ (No. of Positions x (0,80) .0315) + (7,00) .2764 0000000000 (5,00) (3,70).146 0000000000

-FG = Gold Flash -03.0 = 6 mm Stack Height -G $= 10 \mu$ " (0,25 µm) -04.0Gold on = 7 mm Stack Height contact, Gold Flash on tail -07.0 = 10 mm -Н Stack Height $= 30 \mu'$ (0,76 µm) Gold on contact, → (5,50) .217 | ← STACK HEIGHT Α **-03.0** (5,610) .2209

STACK

HEIGHT

Gold Flash on tail MATED HEIGHT (WHEN MATED WITH SEM/SEMS) 6 mm **-04.0** (6,610) .2602 7 mm **-07.0** (9,610) .3783 10 mm *Processing conditions will affect mated height.

PLATING

OPTION

OTHER OPTION **OPTION**

Leave blank for TEMS = (5,50 mm) .217" DIA Polyimide film Pick & = Alignment Pin (Not available with –LC or –WT) Place Pad (Required for TEMS) -LC = Locking Clip (Not available with -A or -WT)

-TR

= Tape & Reel

(Manual placement required) -WT (Required = Weld Tab for TEMS) (Not available with -A or -LC)

Gbps

A OPTION

EXTENDED LIFE PRODUCT 10 year Mixed Flowing Gas with 30µ" Gold Call Samtec for maximum mated cycles

OTHER **SOLUTIONS**

- (1,27 mm) .050" board-to-board and cable-to-board Tiger Eye™ systems available.
- · Board Stacking: See SFM, TFM Series
- · Cable Assemblies: See SFSD, TFSD Series

Contact Samtec.

ALSO AVAILABLE (MOQ Required)

- Other sizes
- Other platings Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

NO. OF **PLATING** TEM 02 DH1 **OPTION** D **OPTION POSITIONS** –A 10, 15, 20, 25, 30, 35, 40, 45, 50 = Alignment Pin = Gold Flash on contact, Matte Tin on tail (Standard sizes) (No. of Positions x (0,80) .0315) + (9,00) .354 ---= 10μ" (0,25 μm) Gold on contact, Matte Tin on tail (8,50) .335 = 30μ" (0,76 μm) Gold on contact, Matte Tin on tail (No. of Positions x (0,80) .0315) + (4,00) .1575 30000000000000000000 (3,70)(0,87)(6,00)146 .034 .236 (1,27)(0,80) -.0315 → (0,25) .010 (6.28)(0,30) → 050 → DIA (0.50).012

-(7,99) .315·

Due to technical progress, all designs, specifications and components are subject to change without notice. ■ WWW.SAMTEC.COM ■

← (No. of Positions x (0,80) .0315) + (7,00) .276